

SAW Filter datasheet

3.0 x 3.0 x 1.1 mm, SMD

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SAW Bandpass Filters | Wireless Communications



Features

Features

- 433.6 MHz center frequency
- Ceramic package for Surface Mounted Technology
- PassBand width: 433.300 to 433.900 MHz
- Low amplitude ripple
- L C matching network required for operation at 50 Ω

Applications

Wireless applications:



3.0 x 3.0 x 1.1 mm

Maximum Ratings

| Parameter | Min. | Тур. | Max. | Unit |
|---|------|------|------|------|
| Storage temperature range (T _{stg}) | -40 | | 85 | °C |
| Operating temperature range (T _A) | -20 | | 85 | °C |
| DC permissive voltage | | | 12 | V |
| Maximum Input Power Level | | | 15 | dBm |
| ESD Voltage (HB) | | | 150 | V |

Frequency and Electrical Characteristics (Reference temperature @ 25°C)

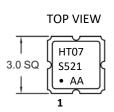
| Parameter | Min. | Typ. ¹ | Max. | Unit |
|--|------|-------------------|------|------|
| Center frequency (f _C) | | 433.92 | | MHz |
| Bandwidth (BW, passband width) | 0.60 | | | MHz |
| Insertion Loss (IL, 433.300 – 433.900 MHz) | | 2.8 | 3.5 | dB |
| Amplitude ripple (433.300 – 433.900 MHz) | | 0.5 | 1.2 | dB |
| Absolute Attenuation | | | | |
| From 0 to 418.5 MHz | 40 | 45 | | |
| From 418.5 to 430.0 MHz | 30 | 35 | | dB |
| From 448.0 to 465.0 MHz | 35 | 40 | | |
| From 465.0 to 1500 MHz | 40 | 45 | | |
| Source impedance (Single ended) | | 50 | | Ω |
| Load impedance (Single ended) | | 50 | | Ω |

¹ Typical values are nominal performances at room temperature

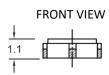




Model Outline, Pin Connection and Marking

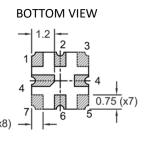


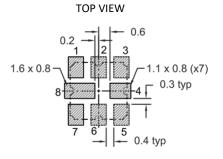
| Marking | | Note |
|---------|------|--|
| Line 1 | HT07 | Rakonxpress designation |
| Line 2 | S521 | S = Production Code 5 = Year 2015 21 = Week 21 |
| Line 3 | •AA | • = Identify black dot AA = Internal Code (Wafer Batch) |



| Pin | Connections |
|------------|-------------|
| 1 | Input |
| 5 | Output |
| 2, 3, 6, 7 | GND |
| 4, 8 | Case Ground |

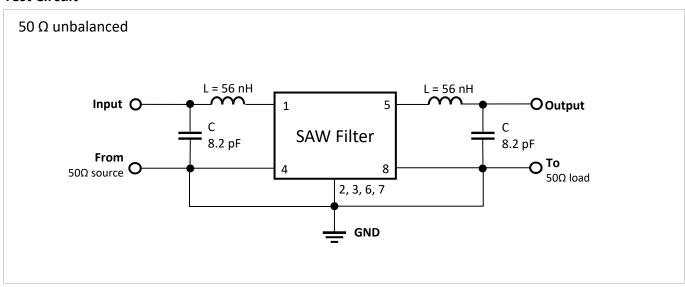
RECOMMENDED PAD LAYOUT





Unit: mm

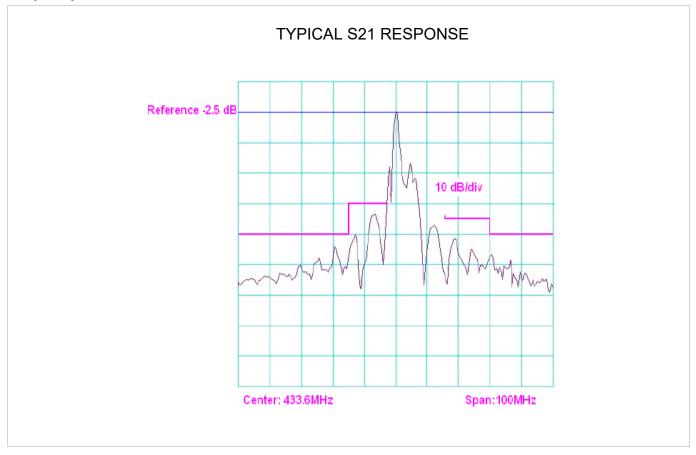
Test Circuit







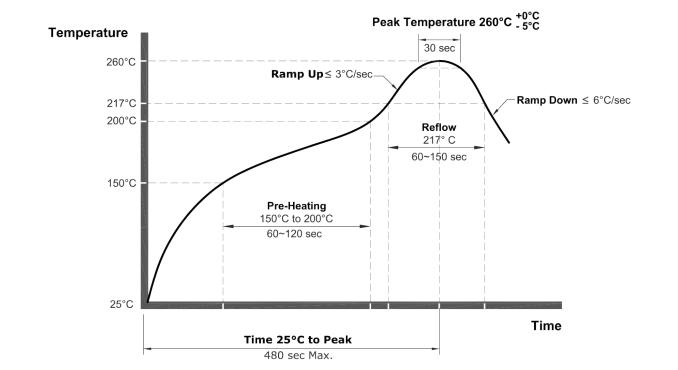
Frequency Characteristics



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Recommended Reflow Soldering Profile



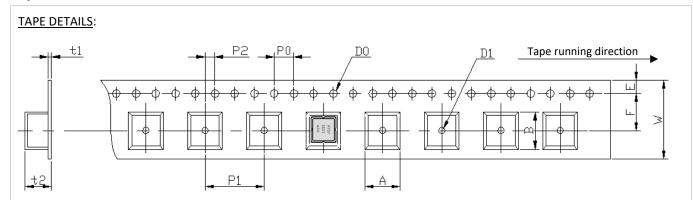
NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at 260 ± 5°C during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350 ± 10 °C during 3~4 seconds. Recovery time: 2 ± 0.5 hour.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of components may be soldered. Please avoid soldering another part of the component.

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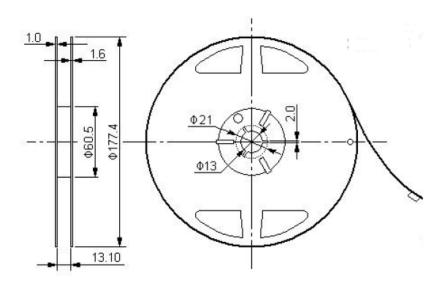


Tape and Reel =



| Parameter | Code | Dimension | Tolerance |
|--|----------------|-----------|-----------|
| Height of component hole | Α | 3.3 max | |
| Width of component hole | В | 3.3 max | |
| Diameter of sprocket hole | D ₀ | Ф 1.5 | ± 0.1 |
| Diameter of feed hole | D ₁ | Ф 1.55 | ± 0.05 |
| Pitch of sprocket hole | P ₀ | 4.0 | ± 0.2 |
| Length from hole center to component center | P ₁ | 4.0 | ± 0.1 |
| Length from Pocket hole center to sprocket hole center | P ₂ | 2.0 | ± 0.05 |
| Width of carrier tape | W | 12.0 | ± 0.1 |
| Width of adhesive tape | F | 5.5 | ± 0.05 |
| Gap of hold down tape and carrier tape | E | 1.75 | ± 0.1 |
| Thickness of Ebossed tape sheet | t1 | 0.31 max | |
| Thickness of Ebossed tape | t2 | 1.7 max | |

REEL DETAILS:



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 2000 pieces/ reel

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Reliability Test

| Parameter | Test condition / Description |
|---------------------|---|
| Thermal Shock | The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40 $^{\circ}$ C $\pm 3^{\circ}$ C, TB=85 $^{\circ}$ C $\pm 2^{\circ}$ C, t1=t2=30min, switch time \leq 3min & cycle time: 100 times, recovery time: 2h \pm 0.5h. |
| Temperature Storage | High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C \pm 2°C for 500 hours, recovery time: 2h \pm 0.5h. |
| | Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C \pm 3°C for 500 hours, recovery time: 2h \pm 0.5h. |
| Humidity test | The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$, and $90^{\circ}95^{\circ}\text{RH}$ for 500 hours. |
| Drop test | The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical specifications. |
| Vibration Fatigue | The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, during 2 hours. |
| Mechanical Shock | The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s 2 , duration 6ms. |
| Note | As a result of the particularity of inner structure of SAW products, the components can easily be breakdown by electrostatic shock; so it's mandatory to pay attention to ESD protect during the tests. |